



Material Content Data Sheet



Sales Product Name		BSZ110N08NS5		Issued		19. January 2018		
MA#		MA001192606						
Package		PG-TSDSON-8-26		Weight*		36.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.419	1.15	1.15	11491	11491
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		270	
	non noble metal	copper	7440-50-8	7.988	21.89		218888	
wire	non noble metal	iron	7439-89-6	0.197	0.54	22.47	5391	224616
	noble metal	gold	7440-57-5	0.030	0.08	0.08	815	815
	plastics	epoxy resin	-	1.921	5.26		52642	
encapsulation	inorganic material	silicondioxide	60676-86-0	16.694	45.74		457427	
	organic material	carbon black	1333-86-4	0.037	0.10	51.10	1022	511091
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10831	10831
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	557	557
solder	noble metal	silver	7440-22-4	0.016	0.04		442	
	non noble metal	tin	7440-31-5	0.013	0.04		353	
	non noble metal	lead	7439-92-1	0.616	1.69	1.77	16877	17672
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		129	
	non noble metal	copper	7440-50-8	3.816	10.46		104559	
	non noble metal	iron	7439-89-6	0.094	0.26	10.73	2575	107295
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		139	
	non noble metal	copper	7440-50-8	4.112	11.27		112683	
	non noble metal	iron	7439-89-6	0.101	0.28	11.56	2775	115632
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com